suction dedicated arm beside a rinse supply arm is also known (refer to Patent Literature 2).

Citation List
Patent Literature
[0004]
Patent Literature 1: JP 2010-50436 A
Patent Literature 2: US Application Publication No. 2016/0016283

Summary of Invention
[0005]
According to a first aspect of the present disclosure, there is provided a substrate processing apparatus including: a table on which a polishing surface for polishing a substrate is provided; and a discharge suction section which includes a plurality of discharge ports which communicates with a fluid supply source and through which a fluid is discharged to the polishing surface and a suction opening which communicates with a vacuum source and through which the fluid existing on the polishing surface is sucked, wherein the table is rotatable, and the plurality of discharge ports are arranged along the rotation direction of the table and the suction opening is arranged between the plurality of discharge ports, and the a plurality of discharge ports are inclined toward the suction port.
[0005a]
According to a second aspect of the present disclosure, there is provided a substrate processing apparatus including: a table on which a polishing surface for polishing a substrate is provided; and a discharge suction section which includes a plurality of discharge ports which communicates with a fluid supply source and through which a fluid is discharged to the polishing surface and a suction opening which communicates with a vacuum source and through which the fluid existing on the polishing surface is sucked wherein the table is rotatable, the plurality of discharge ports are arranged along the rotation direction of the table, the suction opening is arranged on the downstream of the plurality of discharge ports in rotation of the table.

Brief Description of Drawings
[0006]
Fig. 1 is a plan view illustrating the overall structure of a substrate processing apparatus 100 common to

CLAIMS

1. A substrate processing apparatus comprising:

a table on which a polishing surface for polishing a substrate is provided; and

a discharge suction section which includes a plurality of discharge ports which communicates with a fluid supply source and through which a fluid is discharged to the polishing surface and a suction opening which communicates with a vacuum source and through which the fluid existing on the polishing surface is sucked,

wherein the table is rotatable, and the plurality of discharge ports are arranged along the rotation direction of the table and the suction opening is arranged between the plurality of discharge ports, and the a plurality of discharge ports are inclined toward the suction port.

2. A substrate processing apparatus comprising:

a table on which a polishing surface for polishing a substrate is provided; and

a discharge suction section which includes a plurality of discharge ports which communicates with a fluid supply source and through which a fluid is discharged to the polishing surface and a suction opening which communicates with a vacuum source and through which the fluid existing on the polishing surface is sucked

wherein the table is rotatable, the plurality of discharge ports are arranged along the rotation direction of the table, the suction opening is arranged on the downstream of the plurality of discharge ports in rotation of the table.

3. The substrate processing apparatus according to claim 1, wherein

the plurality of discharge ports are disposed on a downstream side of the suction opening in a rotation direction of the table, and

a liquid is supplied from the discharge port.

4. The substrate processing apparatus according to claim 3, wherein

the liquid discharged from the plurality of discharge ports is a processing solution for processing a substrate.

5. The substrate processing apparatus according to any one of claims 1 to 4, wherein

a distance between the discharge port and the suction opening is equal to or more than a lower limit distance within which a range of a thin liquid film on the polishing surface can be expanded by a fluid flow supplied from the discharge port.

6. The substrate processing apparatus according to any one of claims 1 to 5, wherein

a distance between the discharge port and the suction opening is equal to or less than an upper limit distance at which the polishing surface is hit by the fluid discharged from the discharge port to cause the dust and/or debris to float and then the floated dust and/or debris can be sucked from the suction opening.

7. The substrate processing apparatus according to any one of claims 1 to 6, wherein

the discharge port and the suction opening are

positioned on an approximately identical plane.

8. The substrate processing apparatus according to any one of claims 1 to 7, wherein

a plurality of the discharge ports are disposed in a radial direction of the table.

9. The substrate processing apparatus according to any one of claims 1 to 8, further comprising:

a polishing liquid supply section which supplies a polishing liquid to the polishing surface; and

a substrate holding section which holds the substrate, wherein

the discharge suction section is disposed on a downstream side of a polishing liquid supply nozzle in the rotation direction of the table and is disposed on an upstream side of the substrate holding section in the rotation direction of the table.

10. The substrate processing apparatus according to any one of claims 1 to 8, further comprising:

a dresser for performing dressing of the polishing surface; and

a polishing liquid supply section which supplies a polishing liquid to the polishing surface, wherein

the discharge suction section is disposed on a downstream side of the dresser in the rotation direction of the table and is disposed on an upstream side of the polishing liquid supply section in the rotation direction of the table.

11. The substrate processing apparatus according to any one of claims 1 to 8, further comprising:

a substrate holding section which holds the substrate; and

a dresser for performing dressing of the polishing surface, wherein

the discharge suction section is disposed on a downstream side of the substrate holding section in the rotation direction of the table and is disposed on an upstream side of the dresser in the rotation direction of the table.

12. The substrate processing apparatus according to any one of claims 1 to 11, wherein

the size of each of the discharge ports is smaller than that of the suction port.

13. The substrate processing apparatus according to any one of claims 1 to 12, wherein

the discharge suction section has a fan-like shape when the table is viewed from above, and the arc of the discharge suction section has a length proportional to the radius or the outer circumference of the table.

14. The substrate processing apparatus according to any one of claims 1 to 13, wherein

the discharge suction section is provided in plurality.

15. The substrate processing apparatus according to claim 14, further comprising:

a dresser; and

a substrate holding unit,

wherein the plurality of discharge suction sections are both provided downstream of the dresser in the table

rotation direction and upstream of the substrate holding unit in the table rotation direction.

16. The substrate processing apparatus according to claim 14, further comprising:

a dresser; and

a substrate holding unit,

wherein at least one of the plurality of discharge suction sections is provided upstream of the dresser in the direction of rotation of the table and downstream of the substrate holding unit in the direction of rotation of the table, and at least one of the plurality of discharge suction sections is provided downstream of the dresser in the direction of rotation of the table and upstream of the substrate holder in the direction of rotation of the table.

17. The substrate processing apparatus according to claim 2, wherein the discharge suction section further has a plurality of discharge ports arranged on the downstream of the suction opening in rotation of the table.